



Product Change Notification

Change Notification #: 114320 - 00
Change Title: Intel® RAID Maintenance Free Backup
AXXRMFBU5,
PCN 114320-00, Product Design,
Retention Bracket change,
Update to new Super Cap bracket
Date of Publication: January 7, 2016

Key Characteristics of the Change:

Product Design

Forecasted Key Milestones:

Date Customer Must be Ready to Receive Post-Conversion Material *:	Immediate
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** Intel appreciates the customer's desire to receive the latest revision of products. However, Intel manages inventory on a first in first out (FIFO) basis at the MM# level. Subsequently, customer requests for a specific revision of material (below the MM#) will not be supported by Intel.*

Description of Change to the Customer:

Intel is implementing the following change on the Intel® RAID Maintenance Free Backup AXXRMFBU5.

1. Upgrade the Supercap retention bracket with a redesigned, more robust solution.

Customer Impact of Change and Recommended Action:

Intel anticipates no impact to customers, but encourages customers to understand the changes and determine the impact on their applications.

Products Affected / Intel Ordering Codes:

Product Code	MM#	Pre Change TA	Post Change TA
AXXRMFBU5	933907	H29257-003	H29257-004

PCN Revision History:

Date of Revision: January 7, 2016	Revision Number: 00	Reason: Originally Published PCN
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Should you have any issues with the timeline or content of this change, please contact the Intel Representative(s) for your geographic location listed below. No response from customers will be deemed as acceptance of the change and the change will be implemented pursuant to the key milestones set forth in this attached PCN.

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